#### 503662202 01/25/2016

# PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
YEONG BEOM KO	11/02/2015
DONG JIN KIM	11/02/2015
SE WOONG CHA	01/25/2016

### **RECEIVING PARTY DATA**

Name:	AMKOR TECHNOLOGY, INC.	
Street Address:	2045 E. INNOVATION CIRCLE	
City:	TEMPE	
State/Country:	ARIZONA	
Postal Code:	85284	

#### **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	14931112

### CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	60050US02
NAME OF SUBMITTER:	KEVIN E. BORG
SIGNATURE:	/Kevin E. Borg/
DATE SIGNED:	01/25/2016

#### **Total Attachments: 4**

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**PATENT REEL: 037570 FRAME: 0894** 503662202

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PATENT REEL: 037570 FRAME: 0895

## **ASSIGNMENT**

For good and valuable consideration, receipt of which is hereby acknowledged, I,

Yeong Beom Ko	of	202-1305(Sanwol-dong, Buyoung Apt), 22, Cheomdanjungang-ro 68beon-gil, Gwangsan-gu, Gwangju, Korea
Dong Jin Kim	of	205 (Sinchang-dong, Haengbokhanjip), 15-5, Sinchang-ro 106beon-gil, Gwangsan-gu, Gwangju, Korea
Se Woong Cha	of	312, Dongmakgol-gil, Chowol-eup, Kwangju-si, Gyeonggi-do Korea

hereby sell, assign and transfer to Amkor Technology, Inc., a Delaware corporation, having a place of business at 2045 E. Innovation Circle, Tempe, AZ 85284, its successors and assigns, the entire right, title and interest throughout the world in my invention in

# WAFER-LEVEL STACK CHIP PACKAGE AND METHOD OF MANUFACTURING THE SAME

for which I have executed a United States patent application on or about the date of this assignment, and all patent applications and patents of every country for said invention, including divisions, reissues, continuations and extensions thereof, and all rights of priority resulting from the filing of said applications; I authorize the above-named assignee to apply for patents of foreign countries for said invention, and to claim all rights of priority without further authorization from me; I agree to execute all papers useful in connection with said United States and foreign applications, and generally to do everything possible to aid said assignee, its successors, assigns and nominees, at their request and expense, in obtaining and enforcing patents for said invention in all countries; and I request the Commissioner of Patents and Trademarks to issue all patents granted for said invention to the above-named assignee, its successors and assigns.

Attorney Docket No. 15100506-P201507-006US

Executed this da	y of	<u>,</u> 2015
		2 po 140
		YEONG BEOM KO
	Witnessed by	(Full Name)
	Witnessed by:	Signature
		<u> 101 1 7015 </u>
		Date (Control of the Control of the
		Printed Name

Attorney Docket No. 15100506-P201507-006US

Executed this 🔔 day of Nov	_, 2015
	기 등 진
Witnessed by:	DONG JIN KIM (Full Name) Signature
	<u>Nov. 7., 2015</u> Date Do Wun Na
	Printed Name

Attorney Docket No. 15100506-P201507-006US

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PATENT REEL: 037570 FRAME: 0899